

General Plating

TABLE- 1 (Tin-Plated)

Plating Code	Top Plating Thickness		Under Plating Thickness		Area	Match Type
1	80 μ ” Tin Min.	112 μ ” Tin Max. (Pre-tinned)	30 μ Nickel Min.	50 μ ” Nickel Max. (Pre-tinned)	Overall	Crimp clip terminal
		128 μ ” Tin Max. (Post Plating)		50 μ ” Tin Max. (Post Plating)		
	100 μ ” Tin Min.	140 μ ” Tin Max (Pre-tinned)	30 μ Nickel Min.	50 μ ” Nickel Max. (Pre-tinned)	Overall	Solder tail terminal & Board in terminal
		160 μ ” Tin Max (Post Plating)		50 μ ” Tin Max. (Post Plating)		
	120 μ ” Tin Min.	192 μ ” Tin Max.	30 μ Nickel Min.	50 μ Nickel Max.	Overall	Square or round pin
120 μ ” Tin	168 μ ” Tin Max (Pre-tinned)	50 μ Nickel Min.	70 μ ” Nickel Max. (Pre-tinned)	Overall	SMT type terminal	
	192 μ ” Tin Max (Post Plating)		70 μ ” Tin Max. (Post Plating)			
6	120 μ ” Min Tin	168 μ ” Tin Max (Pre-tinned)	50 μ Cu Min.	80 μ Cu Min.	Overall	All type
		192 μ ” Tin Max (Post Plating)				

TABLE- 2 (Gold -Plated)

Plating Code	Top Plating Thickness	Under Plating Thickness		Area	Match Type
		Min.	Max.		
2	0.8 μ ” Gold Min.	50 μ ” Nickel	70 μ ” Nickel	Overall	Square or round pin
	1.2 μ ” Gold Min.	50 μ ” Nickel	70 μ ” Nickel		Other type
3	15 μ ” Gold Min.	50 μ ” Nickel	70 μ ” Nickel	Overall	All type
4	30 μ ” Gold Min.	50 μ ” Nickel	70 μ ” Nickel	Overall	All type
5	50 μ ” Gold Min.	50 μ ” Nickel	70 μ ” Nickel	Overall	All type
7	3 μ ” Gold Min.	50 μ ” Nickel	70 μ ” Nickel	Overall	All type
8	10 μ ” Gold Plated	50 μ ” Nickel		Overall	CP35



Plating Code	Top Plating Thickness	Under Plating Thickness		Area	Match Type
		Min.	Max.		
9	5 μ ” Gold Plated over	50 μ ” Nickel		Overall	All type
A	Selective 1.2 μ ” Gold Flash	50 μ ” Nickel		Contact Area	All type
B	Selective 15 μ ” Gold	50 μ ” Nickel		Contact Area	All type
C	Selective 30 μ ” Gold	50 μ ” Nickel		Contact Area	All type
D	Selective 10 μ ” Gold	50 μ ” Nickel		Contact Area	All type
E	Selective 50 μ ” Gold	50 μ ” Nickel		Contact Area	All type
F	Selective 80 μ ” Gold	50 μ ” Nickel		Contact Area	CP35
G	Selective 5 μ ” Gold	50 μ ” Nickel		Contact Area	CCF
H	Selective 6 μ ” Gold	150 μ ” Tin Min.	50 μ ” Nickel	Contact Area	CJ
I	Selective 15 μ ” Gold	1.2 μ ” Gold Flash Plated over 50 μ ” Nickel		Contact Area	All type
J	Selective 30 μ ” Gold	1.2 μ ” Gold Flash Plated over 50 μ ” Nickel		Contact Area	All type
K	Selective 5 μ ” Gold	80 μ ” Nickel		Contact Area	All type
L	Selective 80 μ ” Gold	80 μ ” Nickel		Contact Area	All type
M	霧錫規格				
N	Selective 3 μ ” Gold	150 μ ” Tin Min.	50 μ ” Nickel	Contact Area	CJ
P	Selective 120 μ ” Gold	50 μ ” Nickel		Contact Area	All type
Q	120 μ ” Matte Tin Min.	52 μ ” Nickel		Contact Area	All type



Plating Code	Top Plating Thickness	Under Plating Thickness		Area	Match Type
		Min.	Max.		
R	50 μ" Tin Min.	50 μ" Nickel Min.		Overall	CP-01100R04
S	Selective 100 μ" Gold	1.2 μ" Gold Flash Plated over 50 μ" Nickel		Contact Area	All type
T	100 μ" Tin Min.	50~100 μ" Nickel Min.		Overall	CII1TSMTPP5-LF
U	20 μ" Gold Plated	50 μ" Nickel		Overall	All type
V	6 μ" Gold Plated	50 μ" Nickel		Overall	All type
W	Selective 3 μ" Gold	1.2 μ" Gold Flash Plated over 50 μ" Nickel		Contact Area	Crimp clip terminal
Y	5 μ" Gold Plated	80 μ" Nickel		Overall	All type
Y	40 μ" Gold Plated	50 μ" Nickel Min.		Overall	CF20
Z	2 μ" Gold Plated	50 μ" Nickel		Overall	All type

SOLDERABILITY:

TEST ITEM	TEST CONDITION	PROCESS	TEST REQUIREMENT
Solder ability	Soldering time: 5±0.5 Second Soldering pot: 230±5°C	Sn - Pb Process	Minimum: 95% of immersed area
	Soldering time: 3±0.5 Second Soldering pot: 245±5°C	Lead Free Process	